

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

*EXAMINER	DOCUMENT	DATE	NAME	INT'L	SUB-	FILING DATE
<u>INITIAL</u>	<u>NUMBER</u>			<u>CLASS</u>	<u>CLASS</u>	<u>(If Appropriate)</u>
<u>AA</u>	<u>6,271,040</u>	<u>08/07/01</u>	<u>Buechler</u>	<u>G01N</u>	<u>21/85</u>	<u>07/30/97</u>
<u>AB</u>	<u>6,296,020</u>	<u>10/02/01</u>	<u>McNeely et al.</u>	<u>F15B</u>	<u>21/00</u>	<u>10/13/99</u>

FOREIGN PATENT DOCUMENTS						
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB- CLASS	TRANSLATION (YES) (NO)
_____	AC	_____	_____	_____	_____	_____ _____
_____	AD	_____	_____	_____	_____	_____ _____
_____	AE	_____	_____	_____	_____	_____ _____

AF Phillip G. Wapner, et al.; "Utilization of surface tension and wettability in the design and operation of microsensors"; Sensors and Actuators B 71 (2000); pp. 60-67.

AG

EXAMINER

DATE CONSIDERED

JCH - 198 - 111a

JACOBSON HOLMAN, PLLC
400 SEVENTH STREET, N.W.
WASHINGTON, D.C. 20004-2201

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

ATTY. DOCKET NO.: P69147US0 GROUP ART UNIT: Not Yet Assigned
SERIAL NO.: New Application FILING DATE: September 29, 2003
APPLICANT(S): Kwang Hyo CHUNG, et al. TODAY'S DATE: September 29, 2003

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	INT'L CLASS	SUB- CLASS	FILING DATE (If Appropriate)
<u>R</u>	AA 6,271,040	08/07/01	Buechler	G01N	21/85	07/30/97
<u>a</u>	AB 6,296,020	10/02/01	McNeely et al.	F15B	21/00	10/13/99

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB- CLASS	TRANSLATION (YES) (NO)
AC						
AD						
AE						

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

R AF Phillip G. Wapner, et al.; "Utilization of surface tension and wettability in the design and operation of microsensors"; Sensors and Actuators B 71 (2000); pp. 60-67.

AG

EXAMINER

DATE CONSIDERED

[Signature] 10/2/05

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).